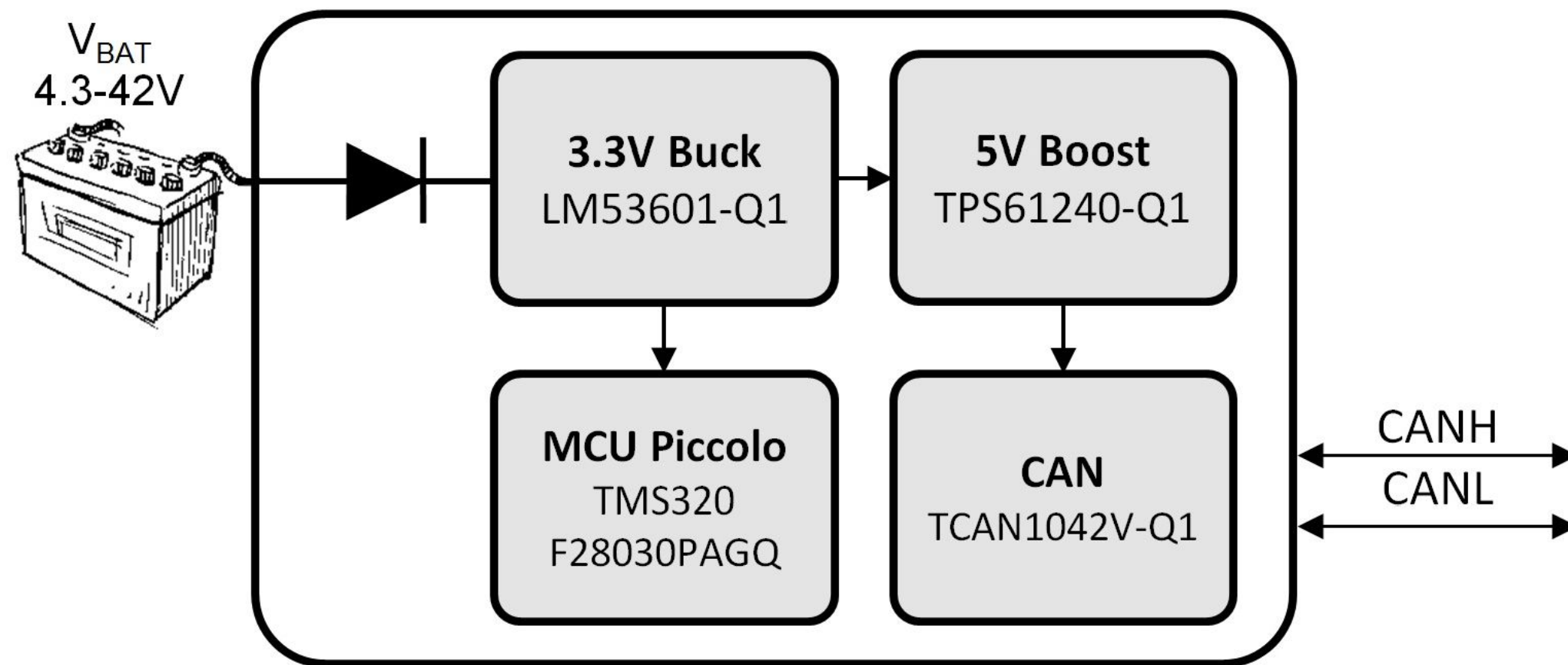


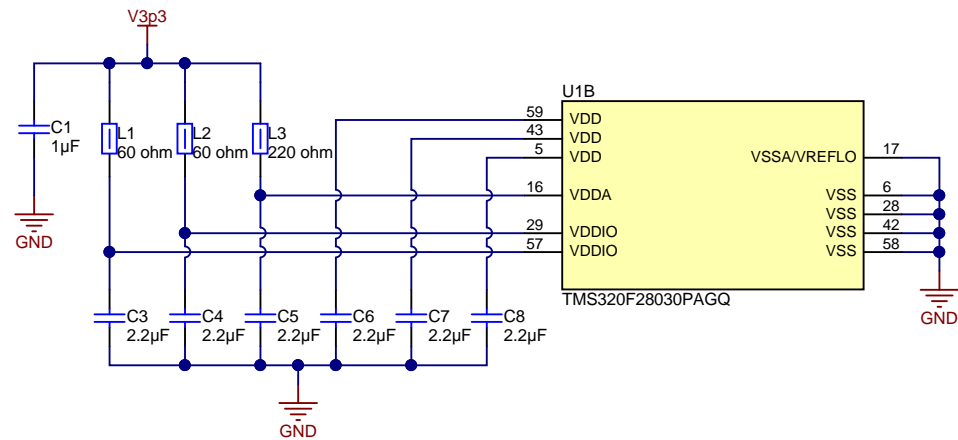
Revision History				
Rev	ECN #	Approved Date	Approved by	Notes
N/A	N/A	N/A	N/A	N/A



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TID #: TIDA-01428	Project Title: Auto Buck, Boost, and CAN Reference Design		
Number: TIDA-01428	Rev: E1	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 4	
Drawn By:	File: TIDA-01428_Buck_Boost_CoverSheet.SchDoc	Size: B	
Engineer: John Griffith	Contact: http://www.ti.com/support		

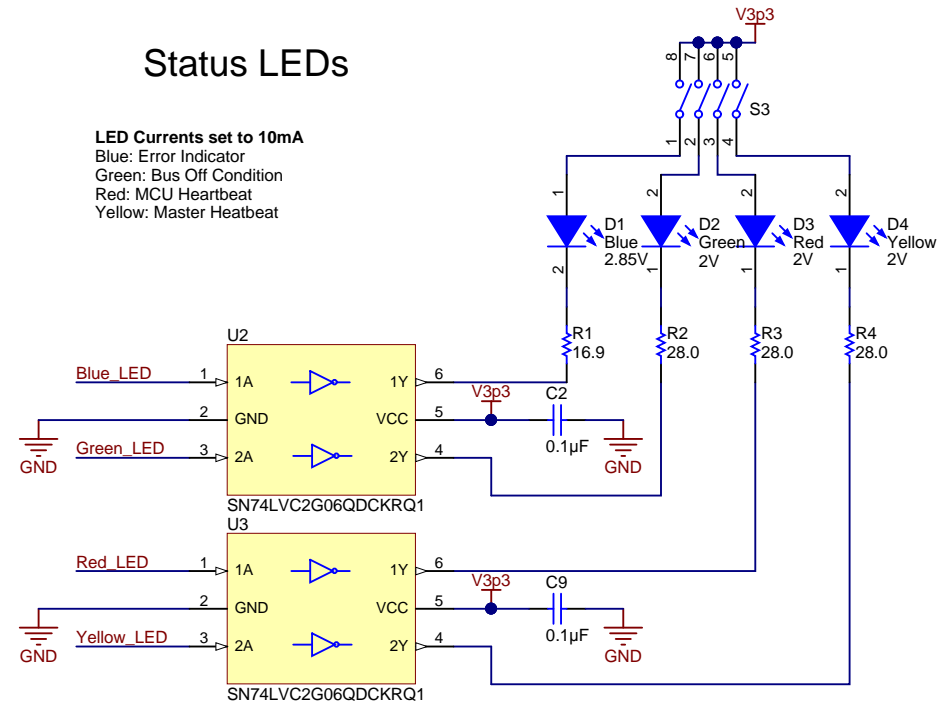
C2000 Power Connections - TMS320F29030Q



Place capacitors as close to VDD pins as possible

Status LEDs

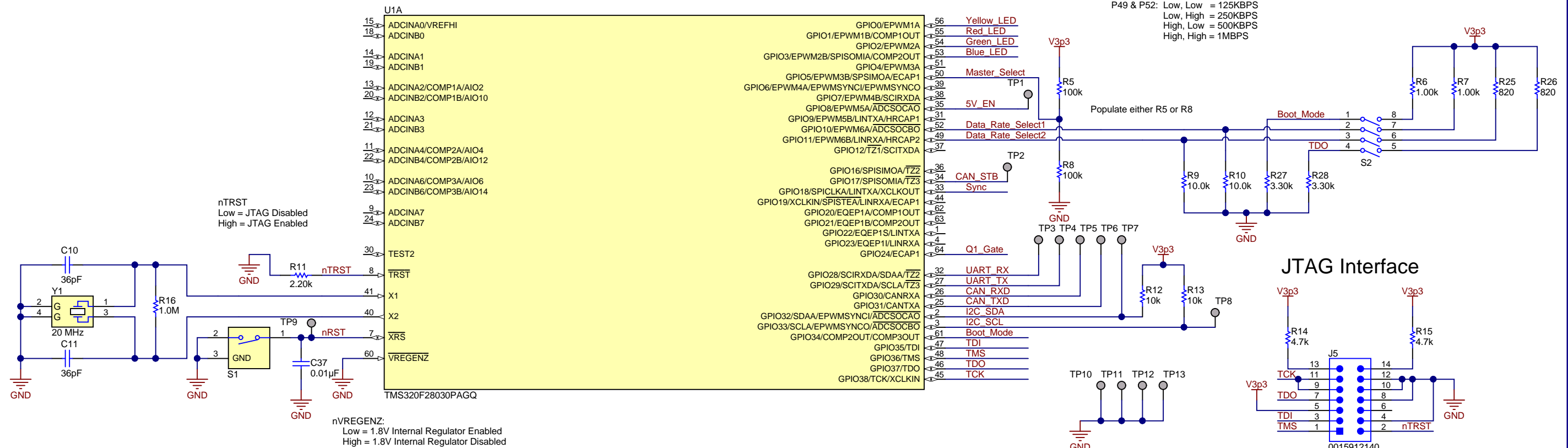
LED Currents set to 10mA
 Blue: Error Indicator
 Green: Bus Off Condition
 Red: MCU Heartbeat
 Yellow: Master Heartbeat



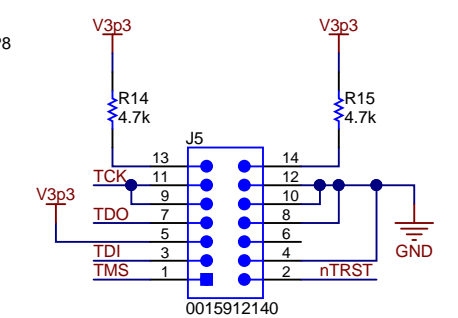
C2000 Peripheral Connections - TMS320F28030Q

Mode Selection DIP Switches

Resistor Selection
 P50: Low = Slave; High = Master
 P49 & P52: Low, Low = 125KBPS
 Low, High = 250KBPS
 High, Low = 500KBPS
 High, High = 1MBPS



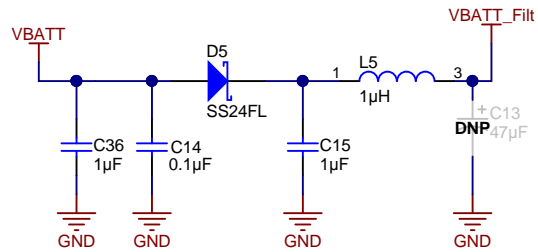
JTAG Interface



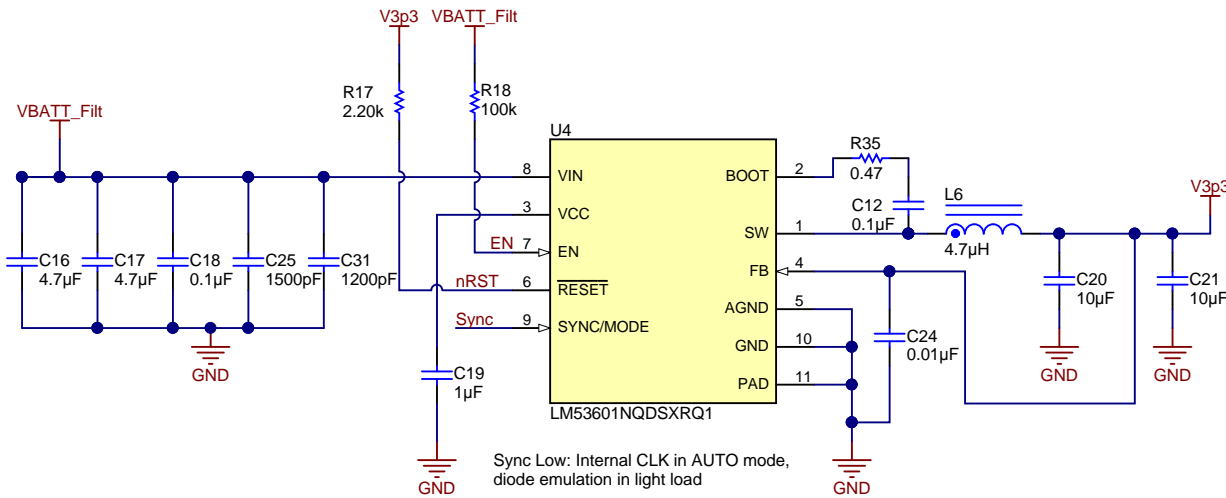
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TID #: TIDA-01428	Project Title: Auto Buck, Boost, and CAN Reference Design	
Number: TIDA-01428	Rev: E1	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 4
Drawn By:	File: TIDA-01428_Buck_Boost_MCU.SchDoc	Size: B
Engineer: John Griffith	Contact: http://www.ti.com/support	

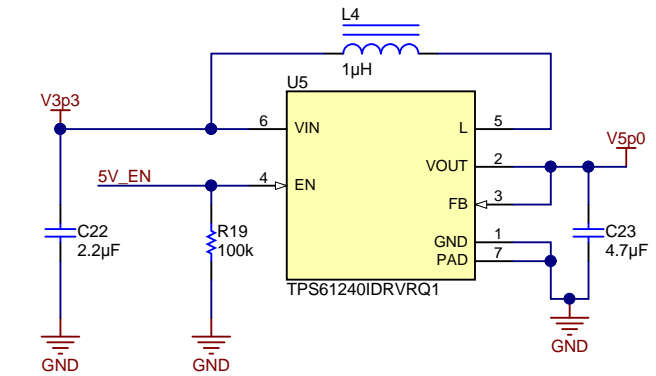
Reverse Battery Protection and Conducted Emissions Filter



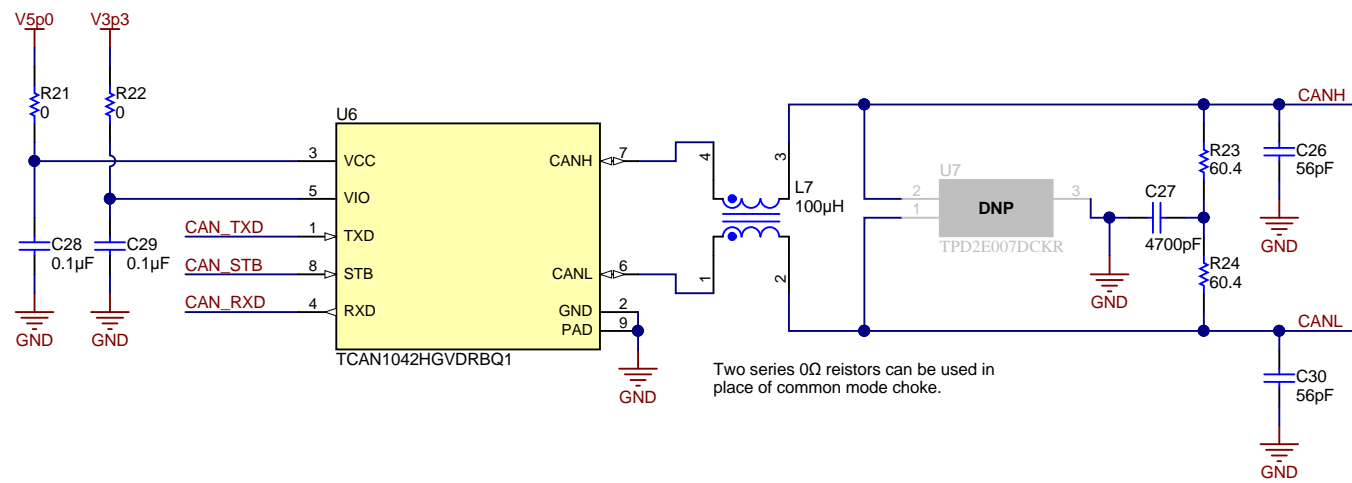
Automotive, 42V Wide VIN, Fixed 3.3V, 1 Amp, 2.1MHz, Synchronous Buck Converter



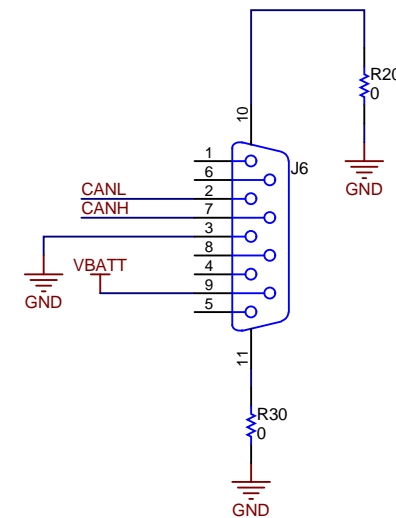
Automotive, Low VIN, Fixed 5.0V, 450mA, 3.5MHz, Synchronous Boost Converter



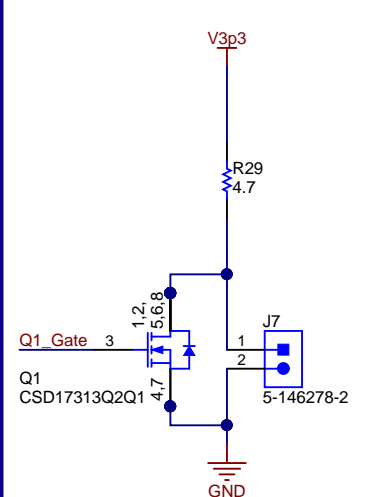
5MBPS CAN FD Transceiver with I/O Level Shifting in DFN Package



External Connector - Female, 9-Pin, DSUB, R/A



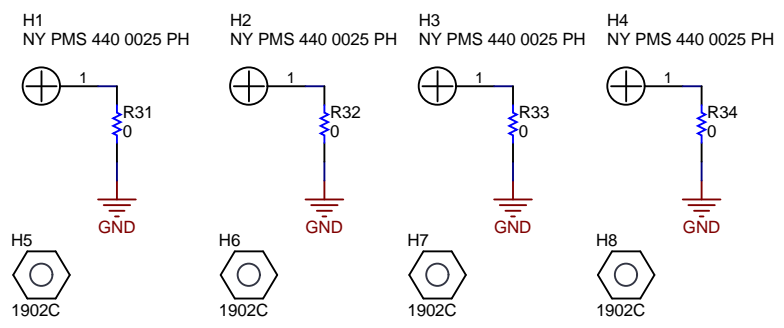
Load Resistor



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TID #: TIDA-01428	Project Title: Auto Buck, Boost, and CAN Reference Design	
Number: TIDA-01428	Rev: E1	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 3 of 4
Drawn By:	File: TIDA-01428_Buck_Boost_Main.SchDoc	Size: B
Engineer: John Griffith	Contact: http://www.ti.com/support	© Texas Instruments 2016





DNP
FID1

DNP
FID2

DNP
FID3

PCB Number: TIDA-01428
PCB Rev: E1

PCB
LOGO
Texas Instruments

PCB
LOGO
Pb-Free Symbol

PCB
LOGO
FCC disclaimer

Variant/Label Table	
Variant	Label Text
001	Standard Build

LBL1
PCB Label
Size: 0.65" x 0.20"

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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Number: TIDA-01428	Rev: E1	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 4 of 4	
Drawn By:	File: TIDA-01428_Buck_Boost_Hardware.SchDoc	Size: B	
Engineer: John Griffith	Contact: http://www.ti.com/support		

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